

SID

Factory: Rot am See

Article:

ML4

Provided:

Customer:

Date:

03.04.2026

WÜRTH
ELEKTRONIK
MORE THAN
YOU EXPECT

Processtechnology: B: undefined

Material Text	Mat. Nr.	μm	Stackup	Process overview
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A-RS Kupferfolie-070my 330x490mm	50200246	70	VS	1	A00 B00
A-RAS-FR4-PP-7628-H45-TG150-HF-EM-37B...	50203002	441		2	
A-RAS-FR4-PP-7628-H45-TG150-HF-EM-37B...	50203002	0		3	
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	0		4	
C-RaS-FR4-DS-2.057mm-070+070-TG150-HF...	50203154	70	L2	5	
		1917			
		70	L3		
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	441		6	
A-RAS-FR4-PP-7628-H45-TG150-HF-EM-37B...	50203002	0		7	
A-RAS-FR4-PP-7628-H45-TG150-HF-EM-37B...	50203002	0		8	
A-RS Kupferfolie-070my 330x490mm	50200246	70	RS	9	

Thickness after Pressing

B00:

3090 μm

Tol+:

320 μm

Tol-:

320 μm

Dmax:

3410 μm

Dmin:

2770 μm

Thickness over all

0 μm

Tol+:

0 μm

Tol-:

0 μm

Dmax:

0 μm

Dmin:

0 μm

Demand for customer

Thickness (D):

3200 μm

Tol+:

320 μm

Tol-:

320 μm

Dmax:

3520 μm

Dmin:

2880 μm

Measuring point: (05) over SM and galv. Cu; both sides

nominal:

3079 μm

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